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74F521 8-Bit Identity Comparator

General Description

The 74F521 is an expandable 8-bit comparator. It compares two words of up to eight bits each and provides a LOW output when the two words match bit for bit. The expansion input $\bar{I}_{A=B}$ also serves as an active LOW enable input.

Features

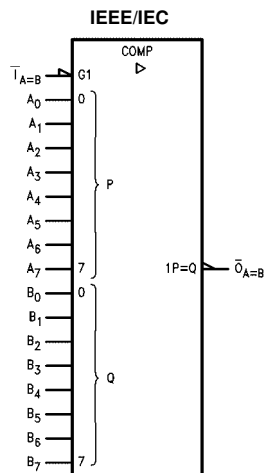
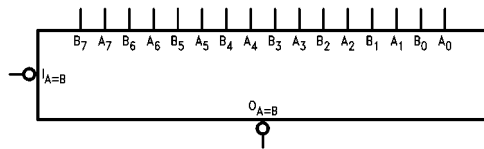
- Compares two 8-bit words in 6.5 ns typ
- Expandable to any word length
- 20-pin package

Ordering Code:

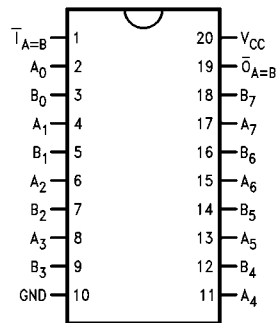
Order Number	Package Number	Package Description
74F521SC	M20B	20-Lead Small Outline Integrated Circuit (SOIC), JEDEC MS-013, 0.300 Wide
74F521SJ	M20D	20-Lead Small Outline Package (SOP), EIAJ TYPE II, 5.3mm Wide
74F521MSA	MSA20	20-Lead Shrink Small Outline Package (SSOP), EIAJ TYPE II, 5.3mm Wide
74F521PC	N20A	20-Lead Plastic Dual-In-Line Package (PDIP), JEDEC MS-001, 0.300 Wide

Devices also available in Tape and Reel. Specify by appending the suffix letter "X" to the ordering code.

Logic Symbols



Connection Diagram



Unit Loading/Fan Out

Pin Names	Description	U.L.	
		HIGH/LOW	Input I_{IH}/I_{IL} Output I_{OH}/I_{OL}
A_0 – A_7	Word A Inputs	1.0/1.0	20 μ A/–0.6 mA
B_0 – B_7	Word B Inputs	1.0/1.0	20 μ A/–0.6 mA
$\bar{I}_{A=B}$	Expansion or Enable Input (Active LOW)	1.0/1.0	20 μ A/–0.6 mA
$\bar{O}_{A=B}$	Identity Output (Active LOW)	50/33.3	–1 mA/20 mA

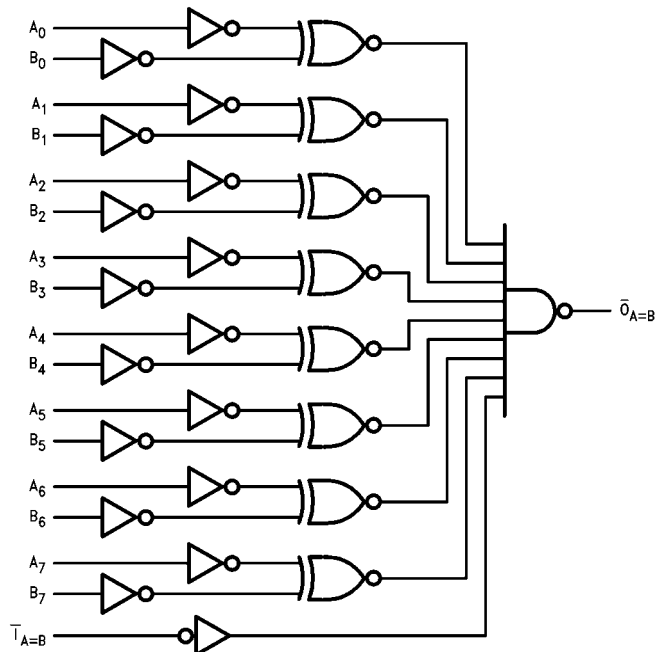
Truth Table

Inputs		Output
$\bar{I}_{A=B}$	A, B	$\bar{O}_{A=B}$
L	A = B (Note 1)	L
L	A \neq B	H
H	A = B (Note 1)	H
H	A \neq B	H

H = HIGH Voltage Level
L = LOW Voltage Level

Note 1: $A_0 = B_0$, $A_1 = B_1$, $A_2 = B_2$, etc.

Logic Diagram



Please note that this diagram is provided only for the understanding of logic operations and should not be used to estimate propagation delays.

Absolute Maximum Ratings(Note 2)

Storage Temperature	-65°C to +150°C
Ambient Temperature under Bias	-55°C to +125°C
Junction Temperature under Bias	-55°C to +150°C
V _{CC} Pin Potential to Ground Pin	-0.5V to +7.0V
Input Voltage (Note 3)	-0.5V to +7.0V
Input Current (Note 3)	-30 mA to +5.0 mA
Voltage Applied to Output in HIGH State (with V _{CC} = 0V)	
Standard Output	-0.5V to V _{CC}
3-STATE Output	-0.5V to +5.5V
Current Applied to Output in LOW State (Max)	twice the rated I _{OL} (mA)

Recommended Operating Conditions

Free Air Ambient Temperature	0°C to +70°C
Supply Voltage	+4.5V to +5.5V

Note 2: Absolute maximum ratings are values beyond which the device may be damaged or have its useful life impaired. Functional operation under these conditions is not implied.

Note 3: Either voltage limit or current limit is sufficient to protect inputs.

DC Electrical Characteristics

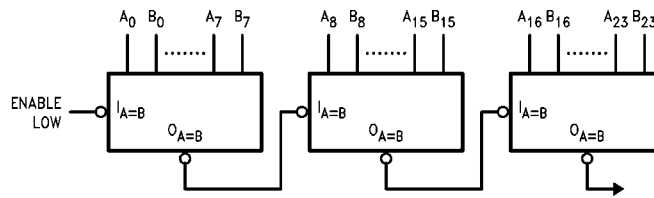
Symbol	Parameter	Min	Typ	Max	Units	V _{CC}	Conditions
V _{IH}	Input HIGH Voltage	2.0			V		Recognized as a HIGH Signal
V _{IL}	Input LOW Voltage			0.8	V		Recognized as a LOW Signal
V _{CD}	Input Clamp Diode Voltage			-1.2	V	Min	I _{IN} = -18 mA
V _{OH}	Output HIGH Voltage	10% V _{CC}	2.5		V	Min	I _{OH} = -1 mA
		5% V _{CC}	2.7				I _{OH} = -1 mA
V _{OL}	Output LOW Voltage			0.5	V	Min	I _{OL} = 20 mA
I _{IH}	Input HIGH Current			5.0	μA	Max	V _{IN} = 2.7V
I _{BVI}	Input HIGH Current Breakdown Test			7.0	μA	Max	V _{IN} = 7.0V
I _{CEX}	Output HIGH Leakage Current			50	μA	Max	V _{OUT} = V _{CC}
V _{ID}	Input Leakage Test	4.75			V	0.0	I _{ID} = 1.9 μA All Other Pins Grounded
I _{OD}	Output Leakage Circuit Current			3.75	μA	0.0	V _{IOD} = 150 mV All Other Pins Grounded
I _{IL}	Input LOW Current			-0.6	mA	Max	V _{IN} = 0.5V
I _{OS}	Output Short-Circuit Current	-60		-150	mA	Max	V _{OUT} = 0V
I _{CCH}	Power Supply Current		21	32	mA	Max	V _O = HIGH

AC Electrical Characteristics

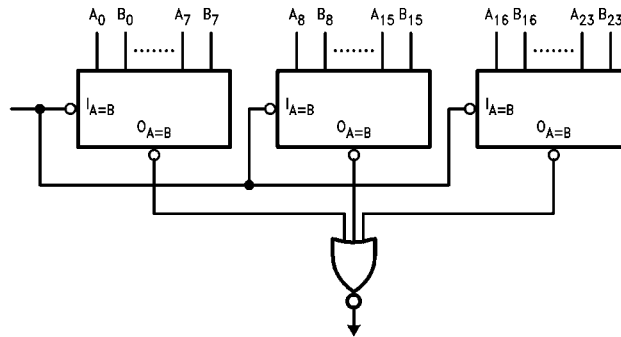
Symbol	Parameter	T _A = +25°C V _{CC} = +5.0V C _L = 50 pF			T _A = -55°C to +125°C V _{CC} = +5.0V C _L = 50 pF		T _A = 0°C to +70°C V _{CC} = +5.0V C _L = 50 pF		Units
		Min	Typ	Max	Min	Max	Min	Max	
		t _{PLH}	Propagation Delay	3.0	7.0	10.0	3.0	14.0	
t _{PHL}	A _n or B _n to $\overline{O_{A=B}}$	4.5	7.0	10.0	4.0	15.0	4.0	11.0	
t _{PLH}	Propagation Delay	3.0	5.0	6.5	3.0	8.5	3.0	7.5	ns
t _{PHL}	$\overline{I_{A=B}}$ to $\overline{O_{A=B}}$	3.5	6.5	9.0	3.5	13.5	3.5	10.0	

Applications

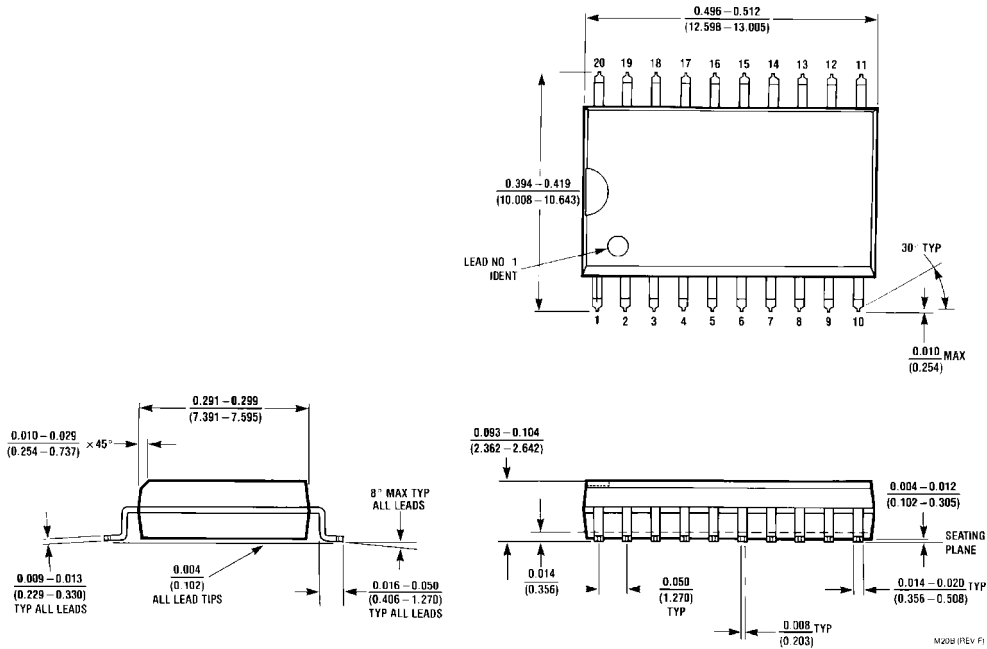
Ripple Expansion



Parallel Expansion

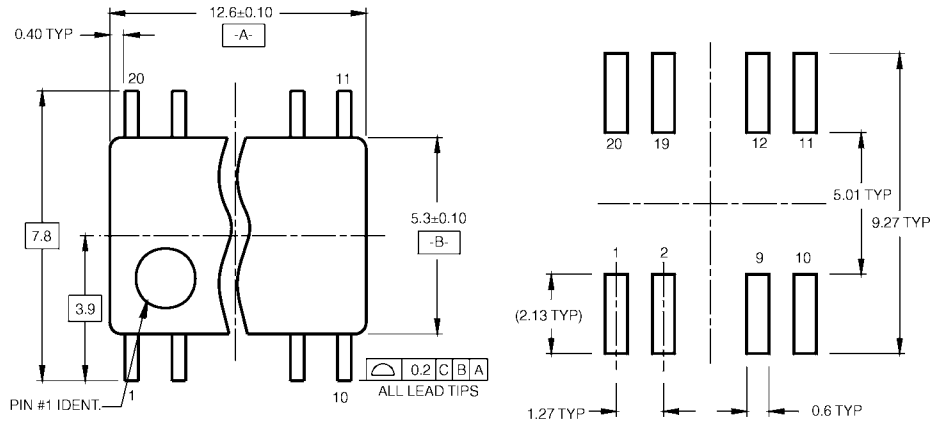


Physical Dimensions inches (millimeters) unless otherwise noted

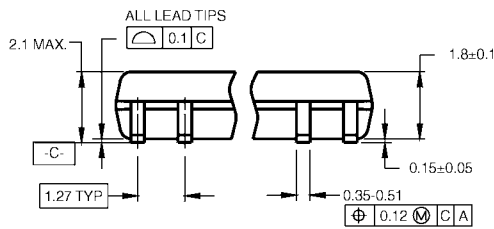


**20-Lead Small Outline Integrated Circuit (SOIC), JEDEC MS-013, 0.300 Wide
Package Number M20B**

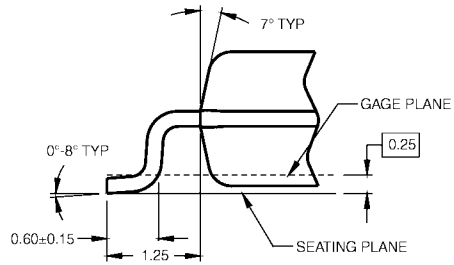
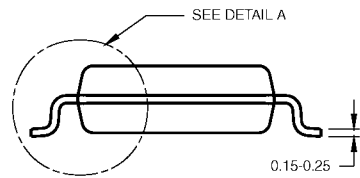
Physical Dimensions inches (millimeters) unless otherwise noted (Continued)



LAND PATTERN RECOMMENDATION



DIMENSIONS ARE IN MILLIMETERS



DETAIL A

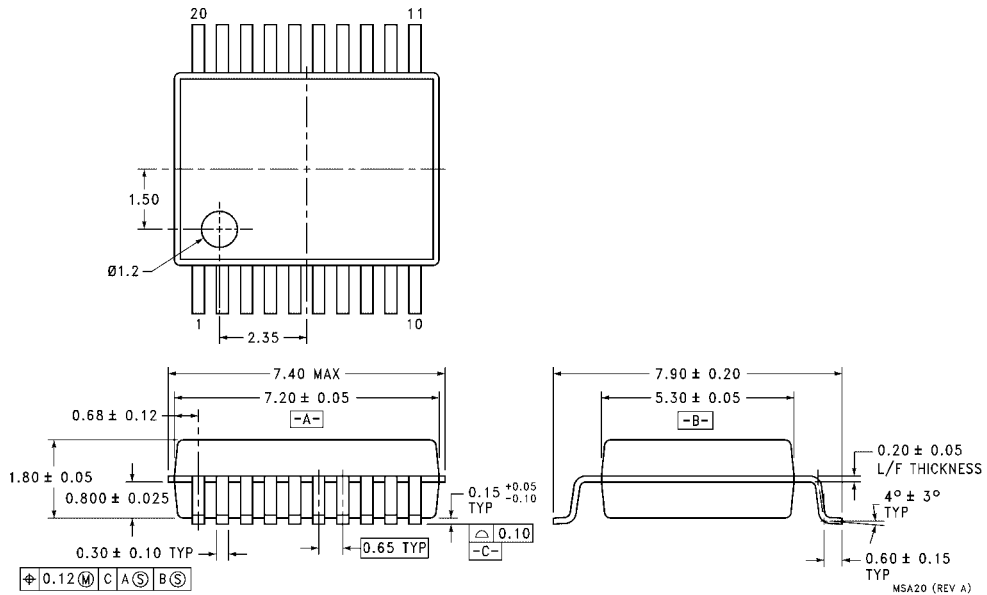
NOTES:

- A. CONFORMS TO EIAJ EDR-7320 REGISTRATION, ESTABLISHED IN DECEMBER, 1998.
- B. DIMENSIONS ARE IN MILLIMETERS.
- C. DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLD FLASH, AND TIE BAR EXTRUSIONS.

M20DRevB1

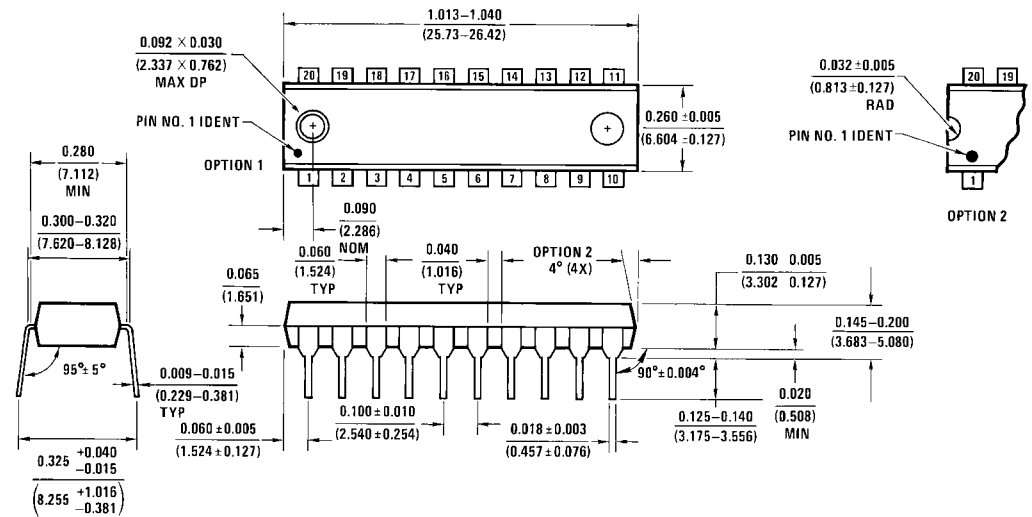
**20-Lead Small Outline Package (SOP), EIAJ TYPE II, 5.3mm Wide
Package Number M20D**

Physical Dimensions inches (millimeters) unless otherwise noted (Continued)



**20-Lead Shrink Small Outline Package (SSOP), EIAJ TYPE II, 5.3mm Wide
Package Number MSA20**

Physical Dimensions inches (millimeters) unless otherwise noted (Continued)



20-Lead Plastic Dual-In-Line Package (PDIP), JEDEC MS-001, 0.300 Wide Package Number N20A

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